

First Call for Papers

International IEEE Conference on the Business of Electronic Product Reliability and Liability
January 13–14, 2003
City University of Hong Kong
Hong Kong, China
January 15–17, 2003
Shenzhen, China

You are cordially invited to submit papers to an International IEEE Conference on the Business of Electronic Product Reliability and Liability. The conference will be held in Hong Kong and Shenzhen, China (transportation to Shenzhen will be provided). The purpose of the Conference is to present the latest advancements in electronic product reliability and liability, and to discuss critical international issues as they affect the global technical and business community. The goal is to help electronics companies design and manufacture cost-effective reliable products, and encourage efficient supply-chain management.

Abstracts and Papers

We currently have 15 industry experts who will be presenting papers on reliability and liability. Papers are now invited from other industry participants as well as researchers from academic and government organizations on the following topics:

- Design for reliability
- Advances in derating
- Screening and burn-in

- Accelerated testing
- Advances in reliability prediction including the new IEEE Standards
- Risks associated with using telecommunications Reliability Standards
- Uprating
- New failure mechanisms in electronic products
- Root-cause analysis

An electronic form of a one-page, 300-word abstract with name, address, phone and fax numbers, and e-mail address must be submitted to the technical committee by e-mail at wywong@ee.cityu.edu.hk on/before August 15, 2002. Instructions for preparing the full paper will be sent to authors whose abstracts are accepted after review. Accepted papers will be published in a formal IEEE Conference Proceedings with an ISBN number. Participants will be required to register for the conference upon notification of acceptance of their full papers.

Important Dates

August 15, 2002 Abstract Submission
 September 15, 2002 Abstract Acceptance
 November 15, 2002 Full Paper Due

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